LITEON®
OPTOELECTRONICS

Photocoupler
Product Data Sheet
LTV-214

Spec No. :DS70-2010-0066
Effective Date: 12/03/2024
Revision: E

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4

LITE-ON Technology Corp. / Optoelectronics
No.90,Chien 1 Road, Chung Ho, New Taipei City 23585, Taiwan, R.O.C.
Tel: 886-2-2222-6181 Fax: 886-2-2221-1948 / 886-2-2221-0660
http://www.liteon.com/opto

Photocoupler
LTV-214-G series

1. DESCRIPTION

1.1 Features

- Current transfer ratio (CTR) : MIN. 20% at I_F = ±1mA, V_{CE} = 5V, Ta=25°C
- High input-output isolation voltage. (Viso=3,750Vrms)
- Employs double transfer mold technology
- ESD pass HBM 8000V / MM2000V
- Package : SSOP4
- Safety approval:

  UL 1577

  VDE DIN EN60747-5-5 (VDE 0884-5)

  CQC GB 4943.1-2022

  CSA CA5A

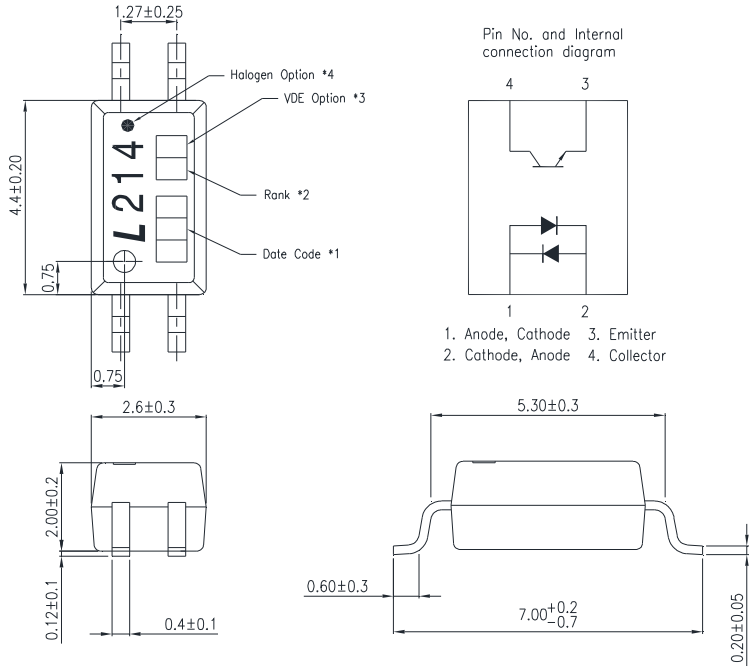
  FIMKO
- RoHS Compliance: All materials be used in device are followed EU RoHS directive (No.2011/65/EU and 2015/863).
- MSL class1
- Halogen free

1.2 Applications

- Hybrid substrates that require high density mounting.
- Programmable controllers
- System appliances, measuring instruments

2. PACKAGE DIMENSIONS

2.1 LTV-214-G series



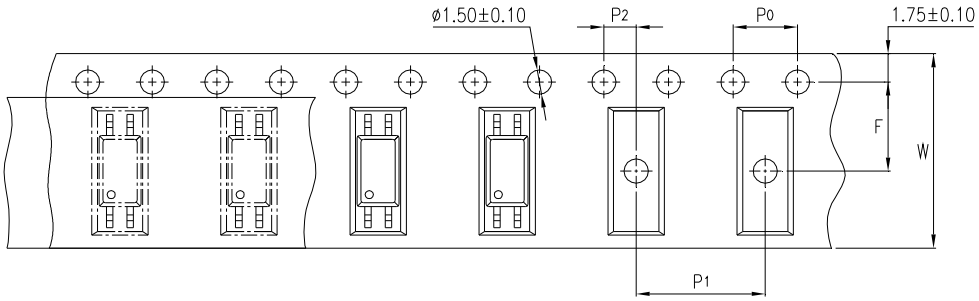
Notes :

1. 1-digit year code, Example : 2010 = A
   2-digit work week ranging from '01' to '52' (01, 03…China -TJ, 02,04…China -CZ)
2. Rank shall be or shall not be marked
3. VDE mark only appears on devices or ordered "V" option.
4. "●" indicates Halogen free option.

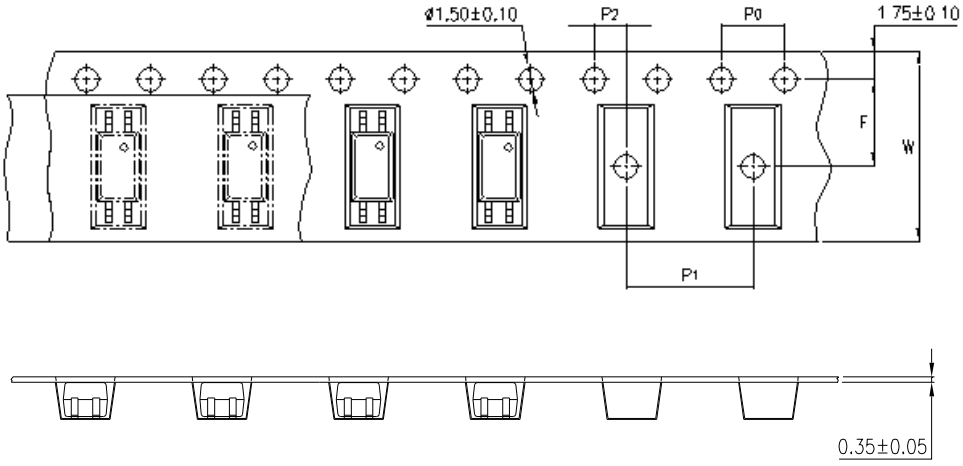
*All dimensions in millimeters.

3. TAPING DIMENSIONS

3.1 LTV-214-G series



3.2 LTV-214-TP1-G series



3.3 Quantities Per Reel

Description	Symbol	Dimension in mm (inch)
Tape wide	W	12±0.3 (0.47)
Pitch of sprocket holes	P_0	4±0.1 (0.15)
Distance of compartment	F	5.5±0.1 (0.217)
	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P_1	8±0.1 (0.315)

Package Type	LTV-214-G series
Quantities (pcs)	3000

4. RATING AND CHARACTERISTICS

4.1 Absolute Maximum Ratings at Ta=25℃

	Parameter	Symbol	Rating	Unit
Input	Forward Current	I_F	±50	mA
	Power Dissipation	P	65	mW
Output	Collector - Emitter Voltage	V_{CEO}	80	V
	Emitter - Collector Voltage	V_{ECO}	7	V
	Collector Current	I_C	50	mA
	Collector Power Dissipation	P_C	150	mW
	Total Power Dissipation	P_{tot}	200	mW
1.	Isolation Voltage	V_{iso}	3750	V_{rms}
	Operating Temperature	T_{opr}	-55 ~ +110	°C
	Storage Temperature	T_{stg}	-55 ~ +150	°C
2.	Soldering Temperature	T_{sol}	260	°C

1. AC For 1 Minute, R.H. = 40 ~ 60%

   Isolation voltage shall be measured using the following method.

   (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.

   (2) The isolation voltage tester with zero-cross circuit shall be used.

   (3) The waveform of applied voltage shall be a sine wave.

2. For 10 Seconds

4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25℃

Parameter			Symbol	Min.	Typ.	Max.	Unit	Test Condition
Input		Forward Voltage	V_F	—	1.2	1.4	V	I_F=±20mA
		Terminal Capacitance	C_t	—	60	—	pF	V=0, f=1KHz
Output		Collector Dark Current	I_{CEO}	—	—	100	nA	V_{CE}=20V, I_F=0
		Collector-Emitter Breakdown Voltage	BV_{CEO}	80	—	—	V	I_C=0.1mA, I_F=0
		Emitter-Collector Breakdown Voltage	BV_{ECO}	7	—	—	V	I_E=10μA, I_F=0
TRANSFER CHARACTERISTICS		Collector Current	I_C	0.2	—	4	mA	I_F=±1mA V_{CE}=5V
	1.	Current Transfer Ratio	CTR	20	—	400	%	
		Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	—	0.4	V	I_F=±8mA I_C=2.4mA
		Isolation Resistance	R_{iso}	5×10^{10}	1×10^{11}	—	Ω	DC500V, 40 ~ 60% R.H.
		Floating Capacitance	Cf	—	0.8	1	pF	V=0, f=1MHz
		Response Time (Rise)	tr	—	3	18	μs	V_{CC}=10V, I_C=2mA, R_L=100Ω, f=100Hz
		Response Time (Fall)	tf	—	4	18	μs	

1. $CTR = \frac{I_C}{I_F} \times 100\%$

5. RANK TABLE OF CURRENT TRANSFER RATIO (CTR)

Model No.	CTR Rank	Min	Max	Condition
LTV-214-G series	0 or No rank	20	400	I_F=±1mA, V_{CE}=5V, Ta=25°C
	A	50	250	
	AK	100	200	
	B	100	400	
	GR	100	300	I_F=±5mA, V_{CE}=5V, Ta=25°C
	GB	100	400	

6. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Figure 1. Collector Power Dissipation vs. Ambient Temperature

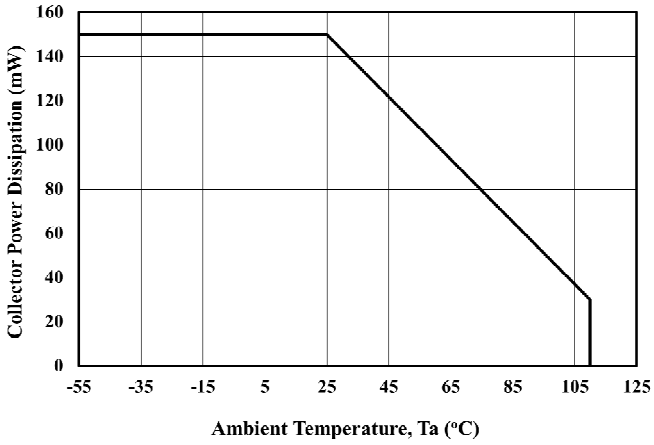


Figure 2. Forward Current vs. Ambient Temperature

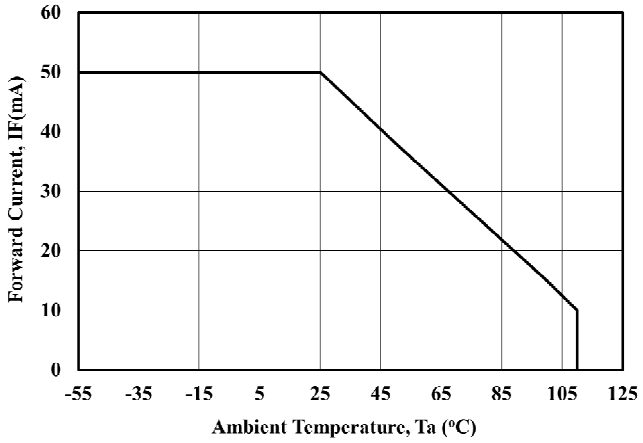


Figure 3. Forward Current vs. Forward Voltage

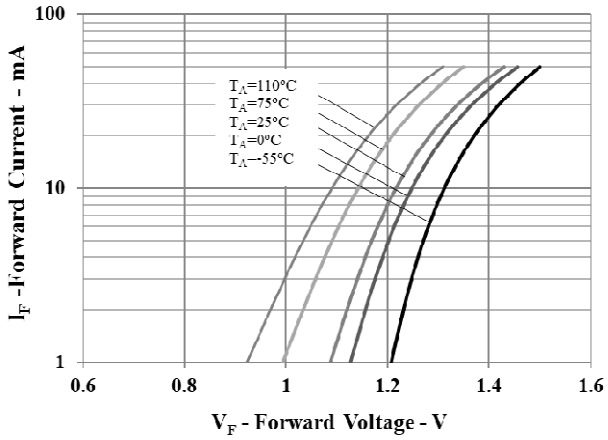


Figure 4. Forward Voltage Temperature Coefficient vs. Forward Current

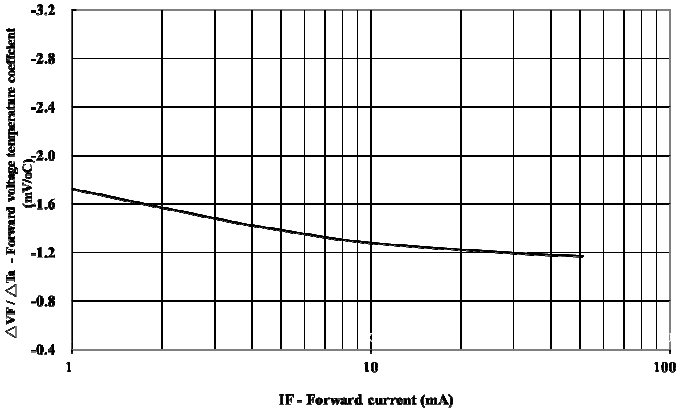


Figure 5. Pulse Forward Current vs. Duty Cycle Ratio

Figure 6. Pulse Forward Current vs. Pulse Forward

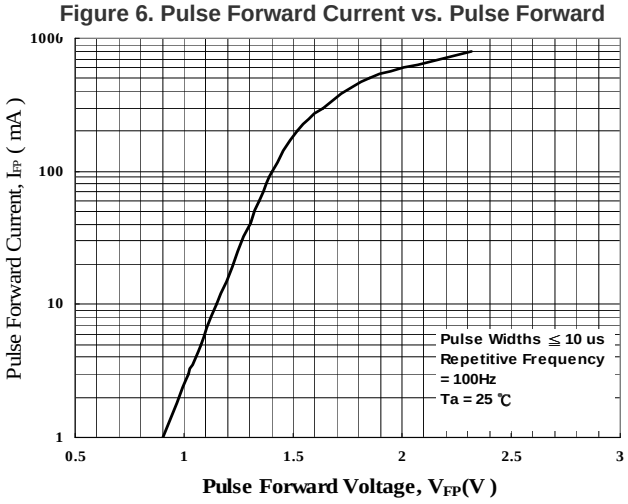


Figure 7. Collector Current vs. Small Collector-Emitter Voltage

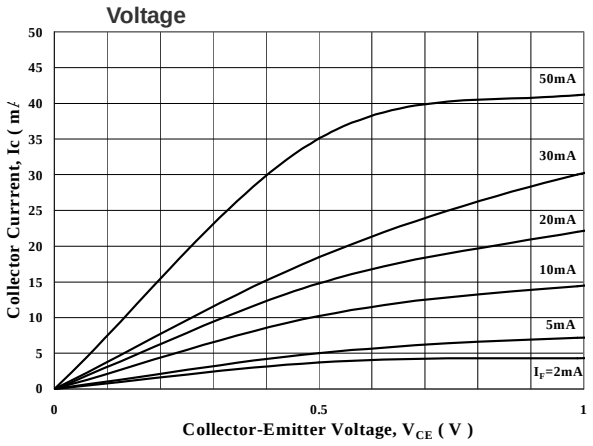


Figure 8. Collector Current vs. Collector-Emitter

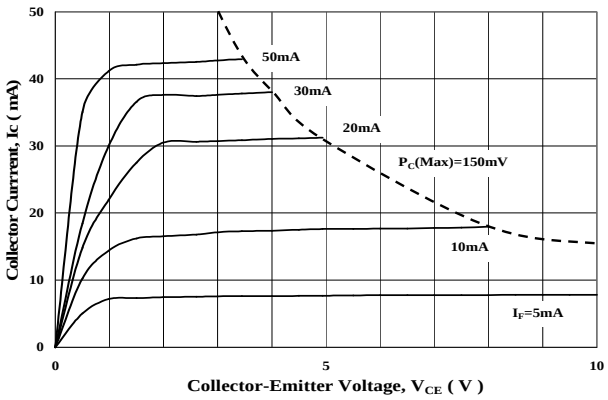


Figure 9. Normalized Collector Current vs. Forward Current

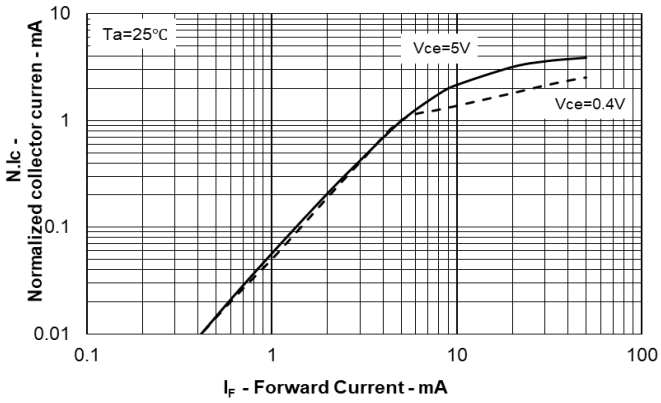


Figure 10. Normalized Current Transfer Ratio vs. Forward Current

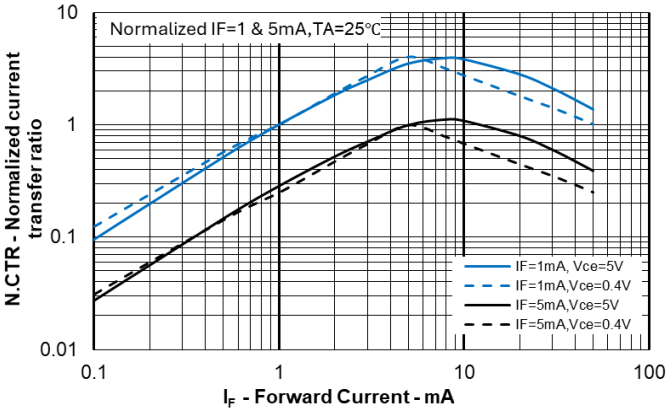


Figure 11. Normalized Current Transfer Ratio vs. Ambient Temperature(Vce=5V)

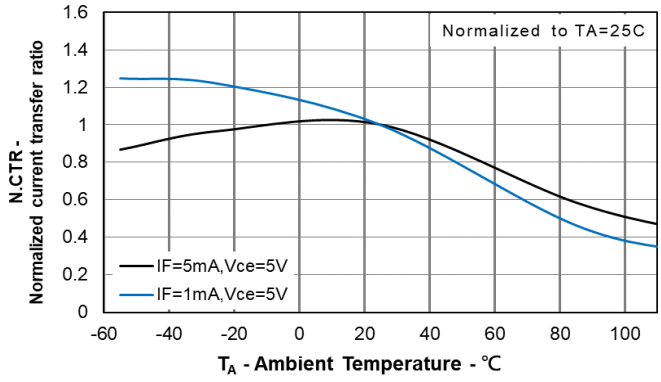
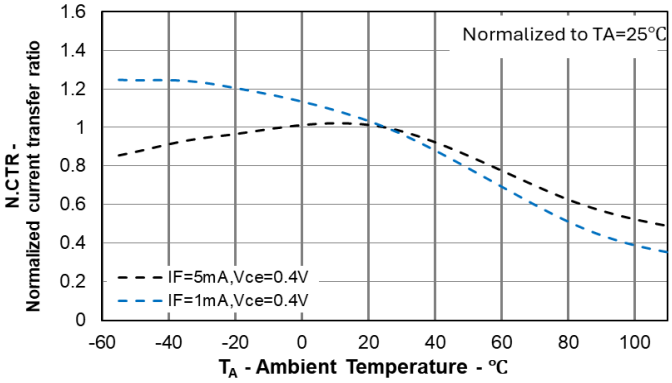


Figure 12. Normalized Current Transfer Ratio vs. Ambient Temperature(Vce=0.4V)



Note: CTR value will decay under high temperature and low current, it is necessary to consider the decay rate by CTR-IF & CTR-TA curve when designing. IF is also recommended to use over 1mA.

Figure 13. Collector Dark Current vs. Ambient Temperature Current

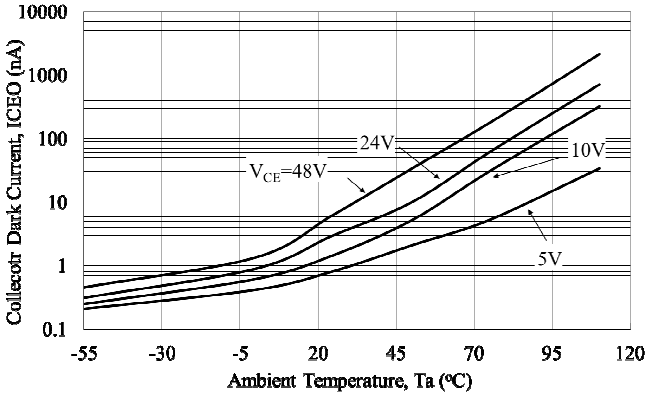


Figure 14. Collector-Emitter Saturation Voltage vs. Ambient Temperature

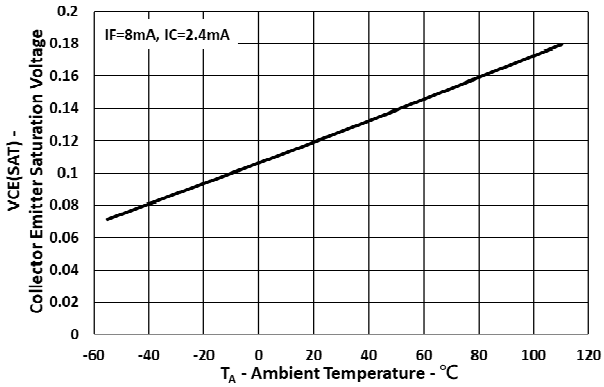


Figure 15. Switching Time vs. Load Resistance

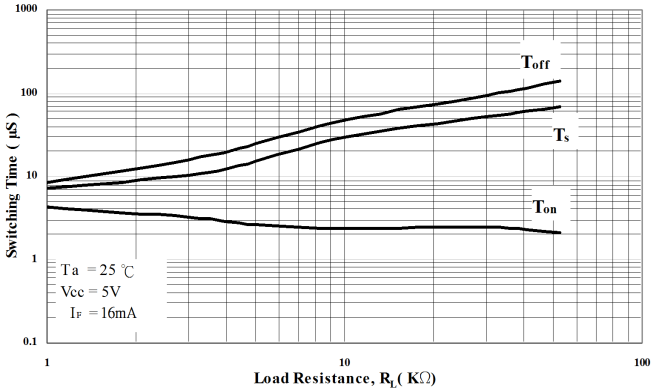


Figure 16. Switching Time vs. Ambient Temperature

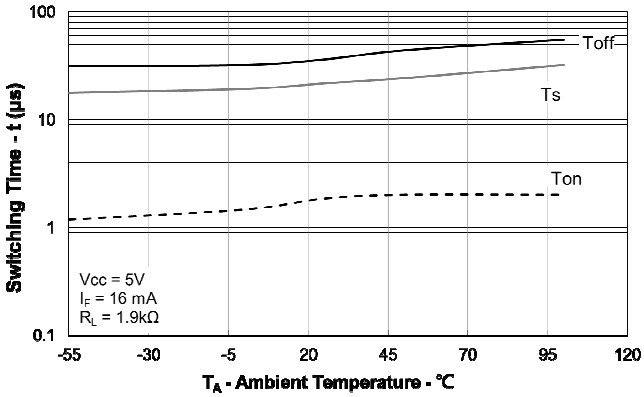
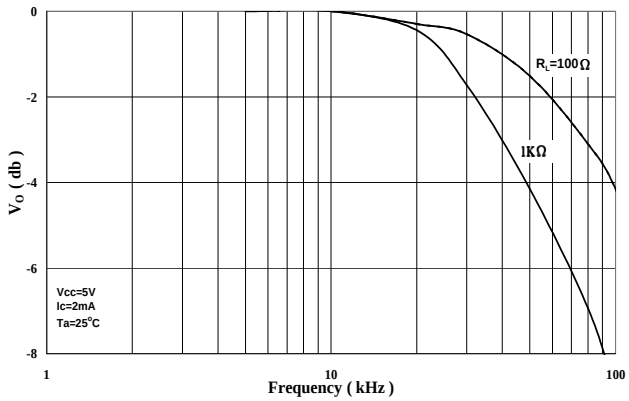
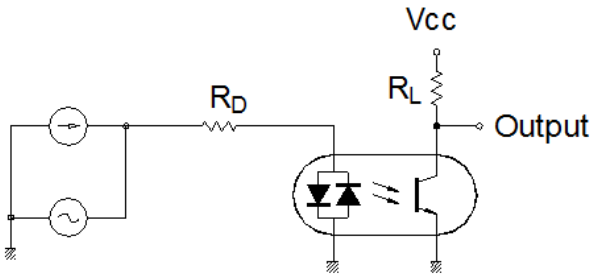


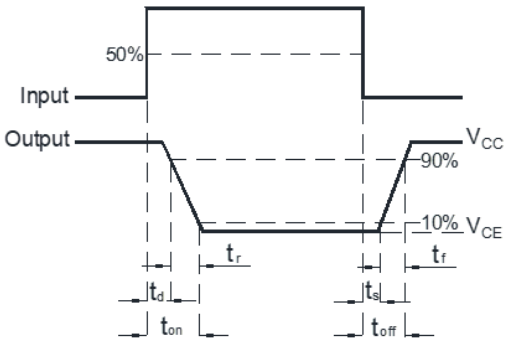
Figure 17. Frequency Response



Note : The above characteristic curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

7. SWITCHING TIME TEST CIRCUIT



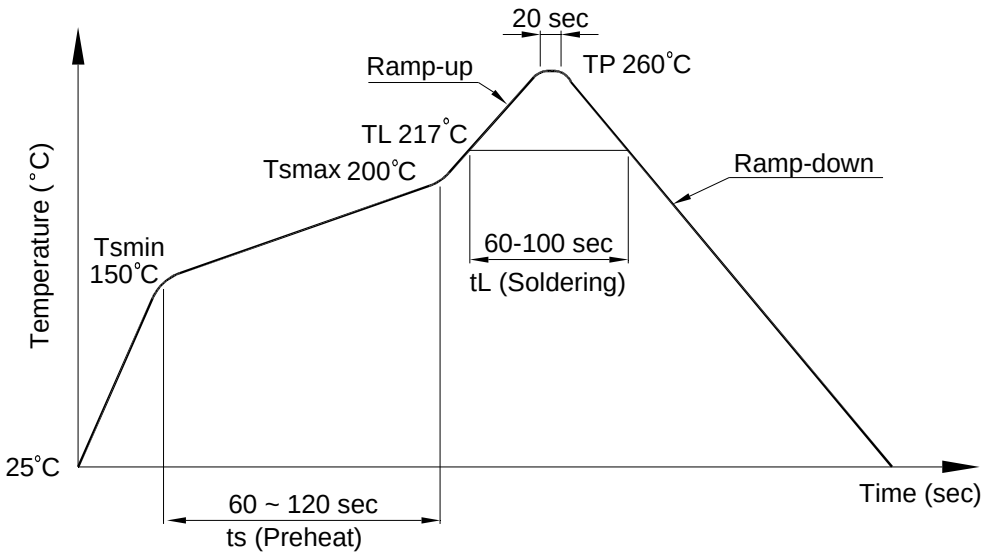


8. TEMPERATURE PROFILE OF SOLDERING

8.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions
Preheat	
- Temperature Min (T_{Smin})	150˚C
- Temperature Max (T_{Smax})	200˚C
- Time (min to max) (ts)	90±30 sec
Soldering zone	
- Temperature (T_L)	217˚C
- Time (t_L)	60 ~ 100 sec
Peak Temperature (T_P)	260˚C
Ramp-up rate	3˚C / sec max.
Ramp-down rate	3~6˚C / sec



8.2 Wave soldering (JEDEC22A111 compliant)

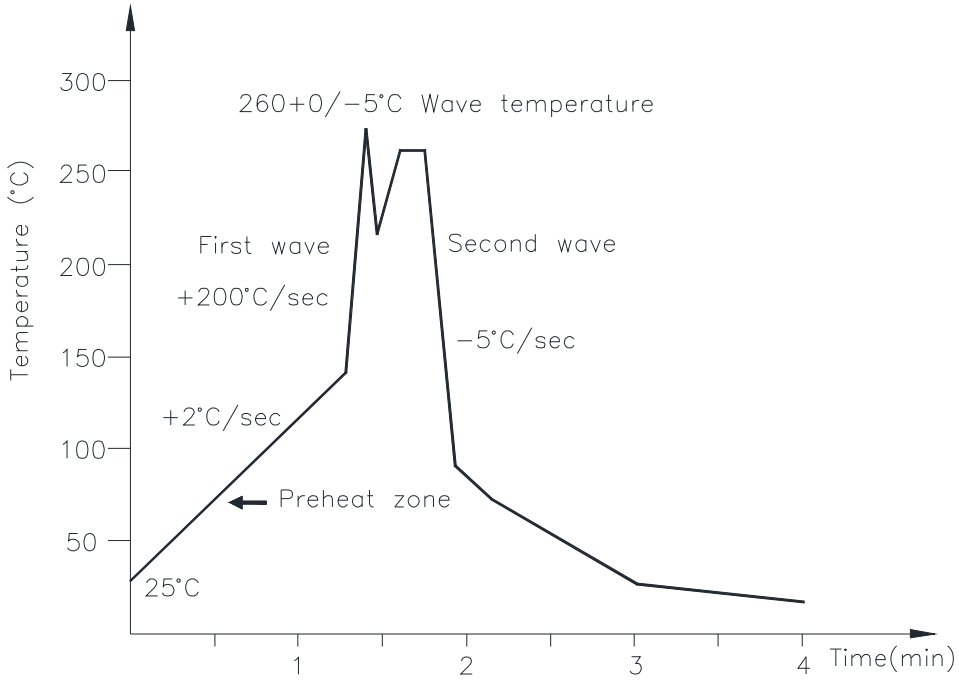
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5˚C

Time: 10 sec.

Preheat temperature:25 to 140˚C

Preheat time: 30 to 80 sec.



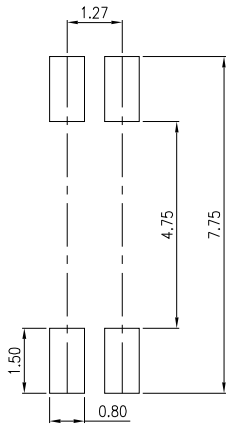
8.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5˚C

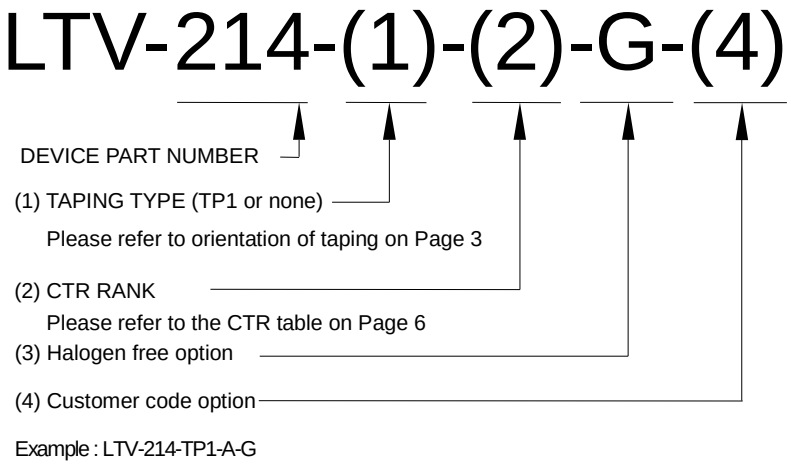
Time: 3 sec max.

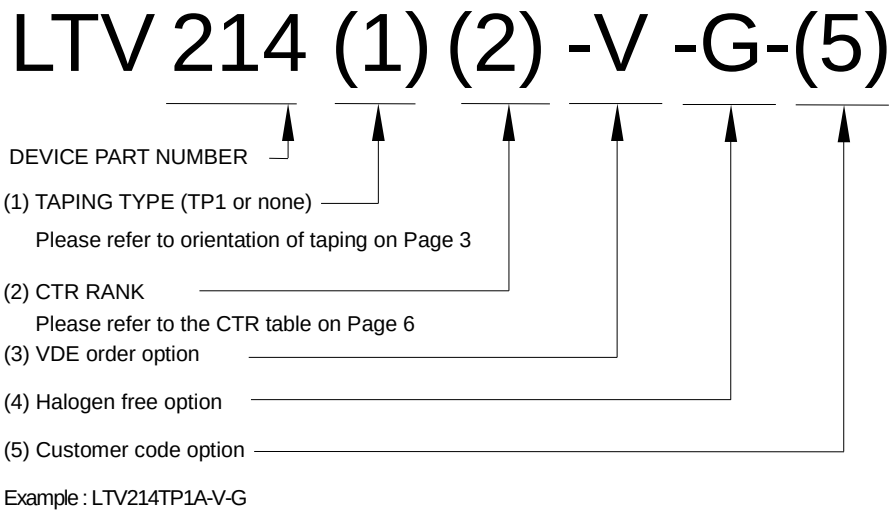
9. RECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)



Unit: mm

10. NAMING RULE





11. NOTES

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any ”specific” application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit’s body in solder paste is not recommended.